



General Description

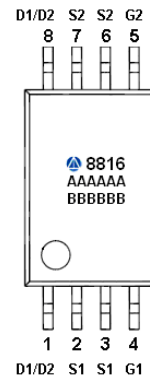
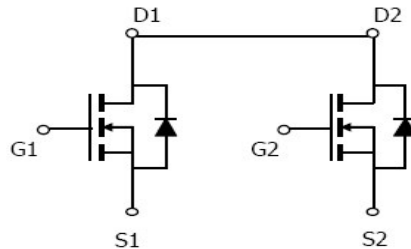
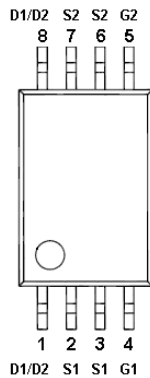
AFN8816, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- 30V/8A, $R_{DS(ON)}=21m\Omega@V_{GS}=10V$
- 30V/5A, $R_{DS(ON)}=24m\Omega@V_{GS}=4.5V$
- 30V/4A, $R_{DS(ON)}=27m\Omega@V_{GS}=2.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- TSSOP-8P package design

Pin Description (TSSOP-8P)



Application

- Load Switch
- Portable Equipment
- Battery Powered System

Pin Define

Pin	Symbol	Description
1	D1 / D2	Drain
2	S1	Source
3	S1	Source
4	G1	Gate
5	G2	Gate
6	S2	Source
7	S2	Source
8	D1 / D2	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN8816TS8RG	8816	TSSOP-8P	Tape & Reel	3000 EA

※ A Lot code

※ B Date code

※ AFN8816TS8RG : 13" Tape & Reel ; Pb- Free ; Halogen- Free



Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	30	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(T _J =150°C)	I _D	T _A =25°C	8.0
		T _A =70°C	4.0
Pulsed Drain Current	I _{DM}	20	A
Continuous Source Current(Diode Conduction)	I _S	1.5	A
Power Dissipation	P _D	T _A =25°C	2.8
		T _A =70°C	1.8
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	62.5	°C/W

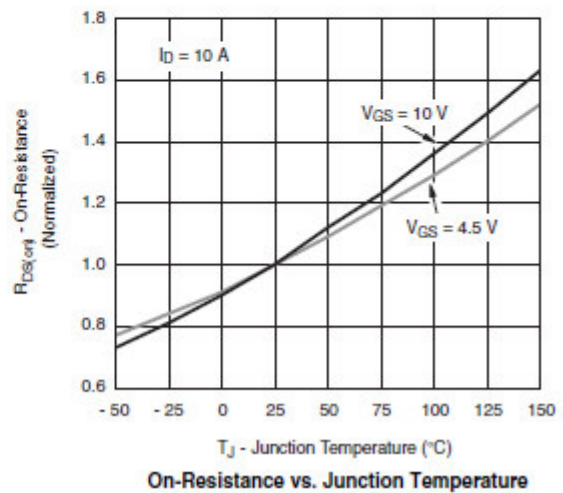
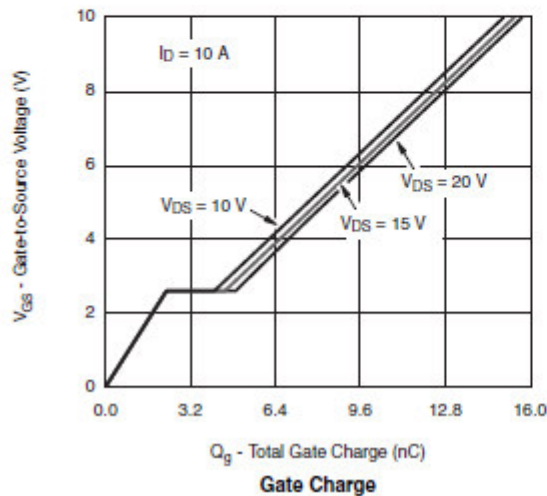
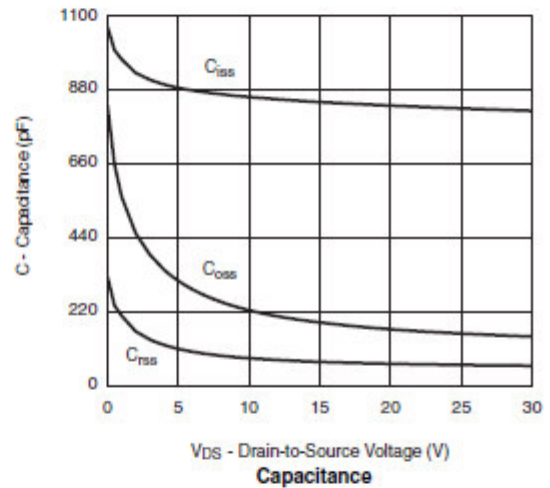
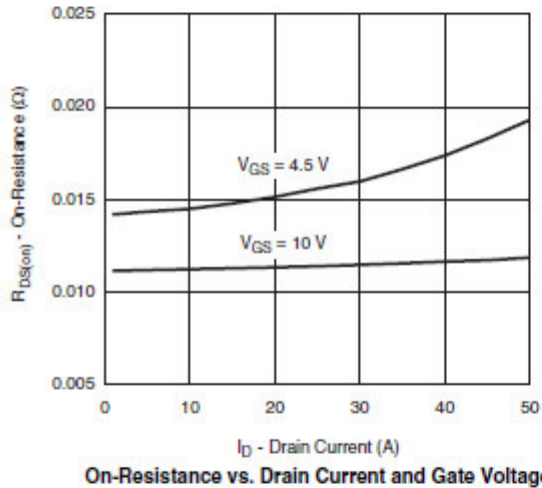
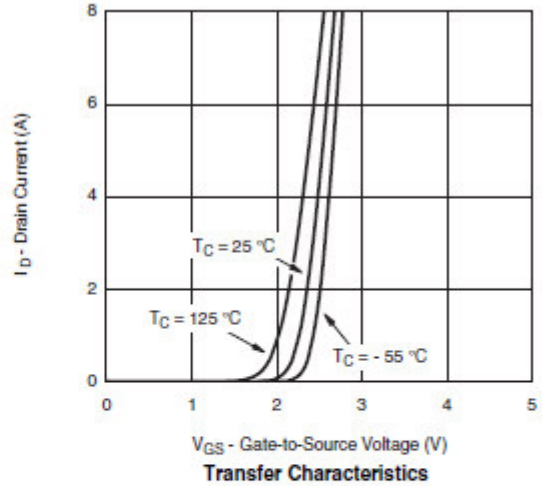
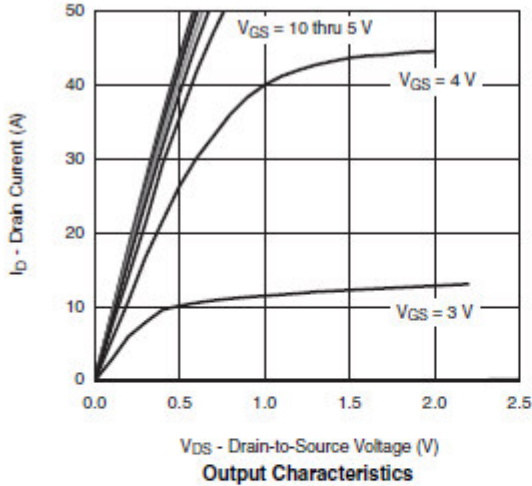
Electrical Characteristics

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.5		1.8	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	uA
		V _{DS} =30V, V _{GS} =0V T _J =85°C			10	
On-State Drain Current	I _{D(on)}	V _{DS} ≥ 5V, V _{GS} =10V	15			A
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =8A		17	21	mΩ
		V _{GS} =4.5V, I _D =5A		18	24	
		V _{GS} =2.5V, I _D =4A		20	27	
Forward Transconductance	g _{FS}	V _{DS} =15V, I _D =10A		24		S
Diode Forward Voltage	V _{SD}	I _S =3.0A, V _{GS} =0V		0.8	1.3	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =15V, V _{GS} =4.5V I _D ≐6A		8	12	nC
Gate-Source Charge	Q _{gs}			2.0		
Gate-Drain Charge	Q _{gd}			2.3		
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V f=1MHz		800		pF
Output Capacitance	C _{oss}			180		
Reverse Transfer Capacitance	C _{rss}			70		
Turn-On Time	t _{d(on)}	V _{DD} =15V, R _L =1.5Ω I _D ≐6A, V _{GEN} =10V R _G =1Ω		8	15	ns
	t _r			8	15	
Turn-Off Time	t _{d(off)}			16	28	
	t _f			8	16	

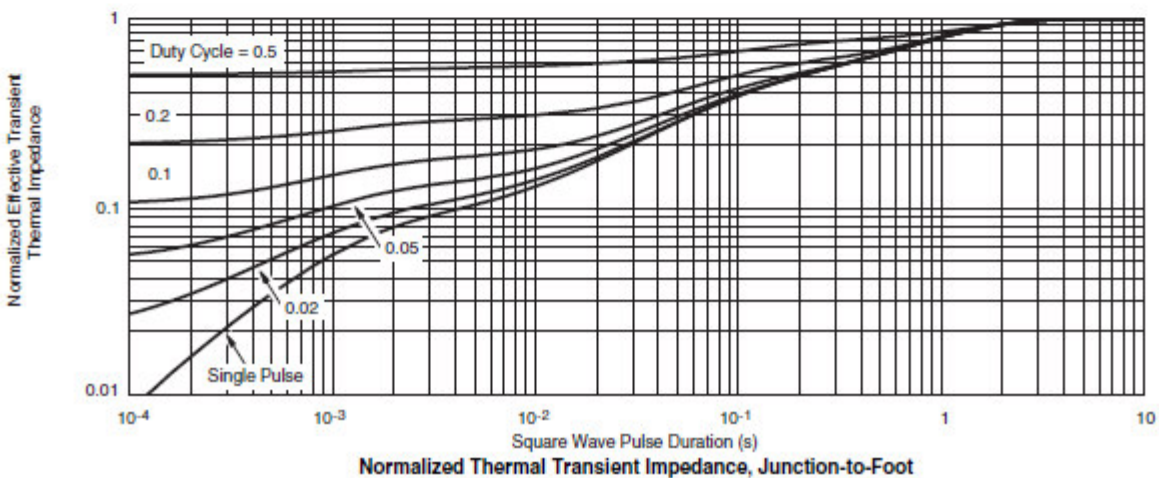
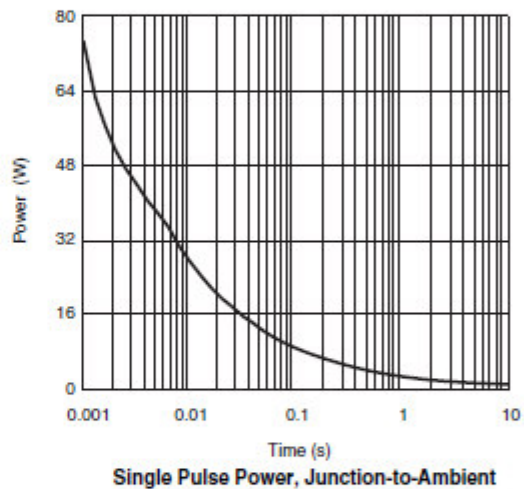
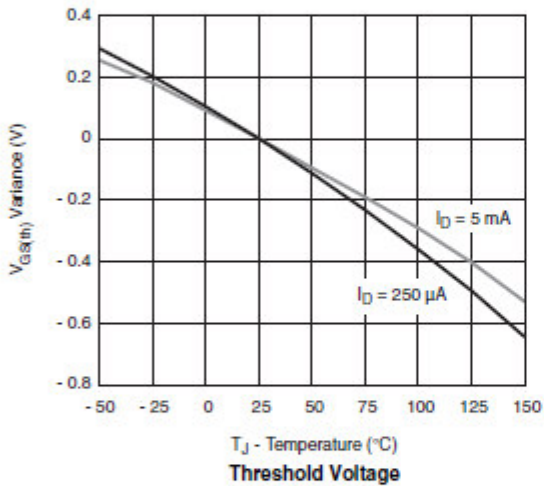
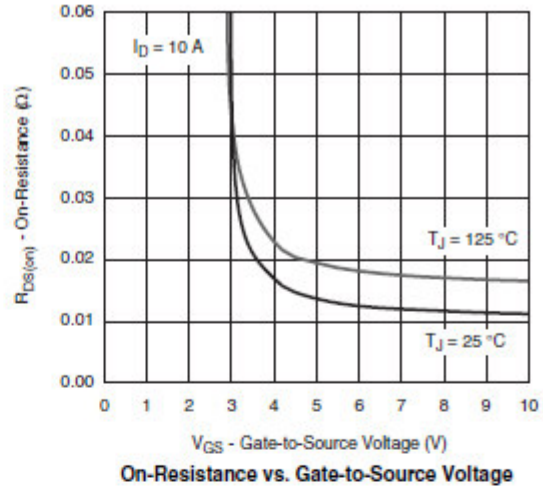
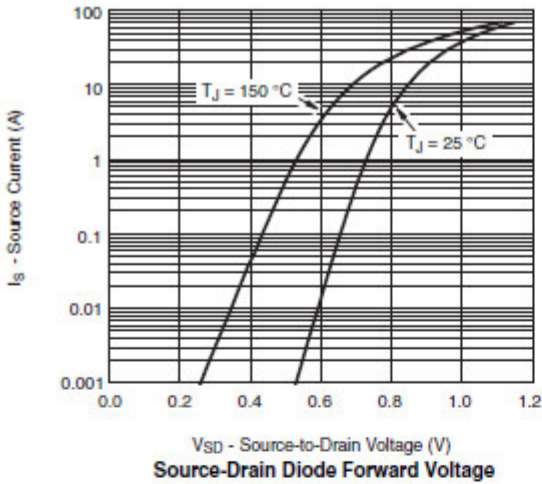


Typical Characteristics





Typical Characteristics



Electrical



Typical Characteristics

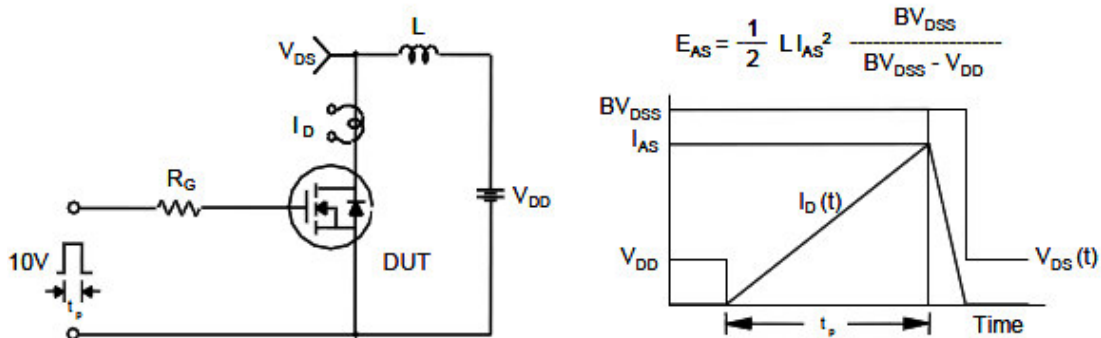
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

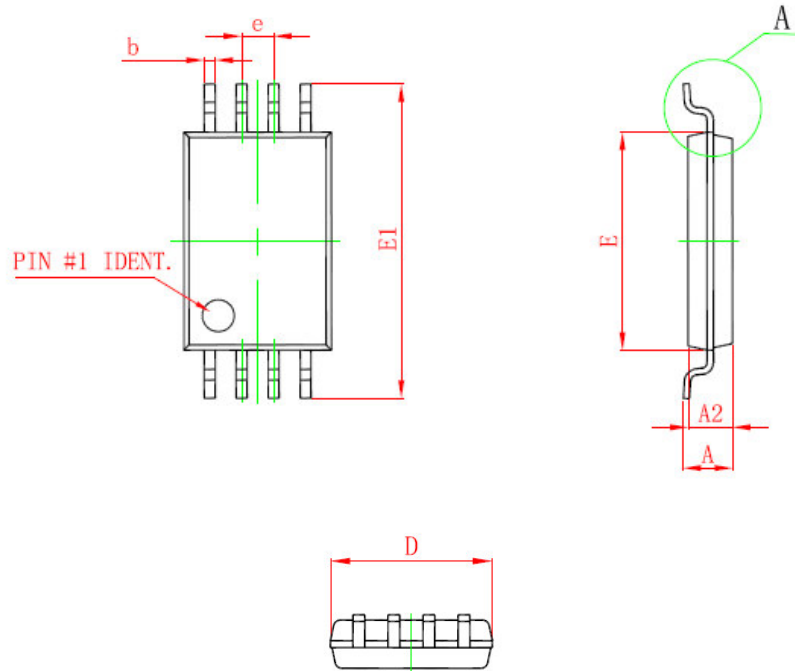


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (TSSOP-8P)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
D	2.900	3.100	0.114	0.122
E	4.300	4.500	0.169	0.177
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
E1	6.250	6.550	0.246	0.258
A		1.100		0.043
A2	0.800	1.000	0.031	0.039
A1	0.020	0.150	0.001	0.006
e	0.65 (BSC)		0.026 (BSC)	
L	0.500	0.700	0.020	0.028
H	0.25 (TYP)		0.01 (TYP)	
θ	1°	7°	1°	7°

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